3D BiCS FLASH™: The Future of High-Density Flash Memory

KIOXIA delivers flash-based products for next-generation storage applications. Having invented NAND flash over 30 years ago, KIOXIA is now one of the world's largest flash memory suppliers – and continues to move the technology forward.

Why 3D Memory?

Moving to a 3D structure was a necessary evolution from 2D floating gate flash, because the memory cell size for 2D flash had shrunk to its limit. Floating gate’s last generation was 15nm, which enabled a density of 128Gb per die. Compared to floating gate, BiCS FLASH 3D flash memory offers higher density, higher endurance, higher performance and better power efficiency. Single die densities of 256Gb and higher are now possible with BiCS FLASH.

What is BiCS FLASH™?

KIOXIA’s BiCS FLASH is a three-dimensional (3D) vertical flash memory cell structure. This structure enables it to surpass the capacity of mainstream 2D (planar) flash memory.

KIOXIA’s TLC 3-bit-per-cell 512Gb (64GB1) BiCS FLASH, an industry first, enhances the reliability of write/erase endurance while boosting write speeds. The company also offers a 1.33Tb BiCS FLASH device that features 4-bit-per-cell, quadruple-level-cell (QLC) technology. It’s the first 3D flash memory device to do so3.

APPLICATIONS

The future of high-density flash memory lies in 3D. Already enabling the enterprise, data center, PC and mobile applications of today, our BiCS FLASH has paved the way for the applications that will turn possibilities into realities. Storage density needs are continually climbing higher and higher – and we designed BiCS FLASH with this in mind.4

- Scott Nelson, Senior Vice President and General Manager, Memory Business Unit, KIOXIA